



INT-A-PAK, Half Bridge - Trench IGBT, 200 A



INT-A-PAK

FEATURES

- Trench IGBT
- Very low $V_{CE(on)}$
- Positive $V_{CE(on)}$ temperature coefficient
- FRED Pt[®] anti-parallel diode low Q_{rr} and low switching energy
- Industry and standard package
- $T_J = 175\text{ °C}$
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT

BENEFITS

- Benchmark efficiency for UPS and welding application
- Rugged transient performance
- Direct mounting on heatsink
- Very low junction to case thermal resistance

PRIMARY CHARACTERISTICS	
V_{CES}	650 V
I_C (DC) at $T_C = 59\text{ °C}$	150 A
$V_{CE(on)}$ (typical) at $I_C = 200\text{ A}$, $T_J = 25\text{ °C}$	1.90 V
Speed	8 kHz to 30 kHz
Package	INT-A-PAK
Circuit configuration	Half bridge

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Collector to emitter voltage	V_{CES}		650	V
Continuous collector current	I_C	$T_C = 25\text{ °C}$	177	A
		$T_C = 80\text{ °C}$	132	
Pulsed collector current	I_{CM}	$T_J = 175\text{ °C}$, $t_p = 6\text{ ms}$, $V_{GE} = 15\text{ V}$	570	
Clamped inductive load current	I_{LM}		600	
Diode continuous forward current	I_F	$T_C = 25\text{ °C}$	138	
		$T_C = 80\text{ °C}$	103	
Maximum non-repetitive peak current	I_{FSM}	10 ms sine or 6 ms rectangular pulse, $T_J = 25\text{ °C}$	700	
Gate to emitter voltage	V_{GE}		± 20	V
Maximum power dissipation	IGBT	$T_C = 25\text{ °C}$	429	W
		$T_C = 80\text{ °C}$	271	
	Diode	$T_C = 25\text{ °C}$	288	
		$T_C = 80\text{ °C}$	183	
RMS isolation voltage	V_{ISOL}	$T_J = 25\text{ °C}$, $f = 50\text{ Hz}$, $t = 1\text{ s}$	3500	V
Operating junction temperature range	T_J		-40 to +175	$^{\circ}\text{C}$



ELECTRICAL SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Collector to emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE} = 0\text{ V}, I_C = 400\text{ }\mu\text{A}$	650	-	-	
Collector to emitter voltage	$V_{CE(on)}$	$V_{GE} = 15\text{ V}, I_C = 100\text{ A}$	-	1.49	-	V
		$V_{GE} = 15\text{ V}, I_C = 200\text{ A}$	-	1.90	2.12	
		$V_{GE} = 15\text{ V}, I_C = 100\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	1.62	-	
		$V_{GE} = 15\text{ V}, I_C = 200\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	2.20	-	
Gate threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}, I_C = 2.0\text{ mA}$	2.9	4.0	5.3	
Temperature coefficient of threshold voltage	$\Delta V_{GE(th)}/\Delta T_J$	$V_{CE} = V_{GE}, I_C = 2.0\text{ mA}$ ($25\text{ }^\circ\text{C}$ to $125\text{ }^\circ\text{C}$)	-	-10	-	mV/ $^\circ\text{C}$
Forward transconductance	g_{fe}	$V_{CE} = 20\text{ V}, I_C = 200\text{ A}$	-	200	-	S
Transfer characteristics	V_{GE}	$V_{CE} = 20\text{ V}, I_C = 200\text{ A}$	-	6.6	-	V
Collector to emitter leakage current	I_{CES}	$V_{GE} = 0\text{ V}, V_{CE} = 650\text{ V}$	-	0.3	200	μA
		$V_{GE} = 0\text{ V}, V_{CE} = 650\text{ V}, T_J = 125\text{ }^\circ\text{C}$	-	0.1	-	mA
Diode forward voltage drop	V_{FM}	$I_{FM} = 100\text{ A}$	-	1.75	-	V
		$I_{FM} = 200\text{ A}$	-	2.08	3.04	
		$I_{FM} = 100\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	1.41	-	
		$I_{FM} = 200\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	1.80	-	
Gate to emitter leakage current	I_{GES}	$V_{GE} = \pm 20\text{ V}$	-	-	200	nA

SWITCHING CHARACTERISTICS							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Total gate charge (turn-on)	Q_g	$I_C = 200\text{ A}$	-	476	-	nC	
Gate to emitter charge (turn-on)	Q_{ge}	$V_{CC} = 520\text{ V}$	-	61	-		
Gate to collector (turn-on)	Q_{gc}	$V_{GE} = 15\text{ V}$	-	128	-		
Turn-on switching loss	E_{on}	$V_{CC} = 325\text{ V}, I_C = 200\text{ A}, R_g = 4.7\text{ }\Omega,$ $L = 500\text{ }\mu\text{H}, V_{GE} = 15\text{ V}$	-	2.34	-	mJ	
Turn-off switching loss	E_{off}		-	3.77	-		
Total switching loss	E_{tot}		-	6.11	-		
Turn-on switching loss	E_{on}	$V_{CC} = 325\text{ V}, I_C = 200\text{ A}, R_g = 4.7\text{ }\Omega,$ $L = 500\text{ }\mu\text{H}, V_{GE} = 15\text{ V}$ $T_J = 125\text{ }^\circ\text{C}$	-	2.82	-	mJ	
Turn-off switching loss	E_{off}		-	3.86	-		
Total switching loss	E_{tot}		-	6.68	-		
Turn-on delay time	$t_{d(on)}$			-	79	-	ns
Rise time	t_r			-	82	-	
Turn-off delay time	$t_{d(off)}$			-	306	-	
Fall time	t_f	-		34	-		
Reverse bias safe operating area	RBSOA	$I_C = 600\text{ A}, R_g = 27\text{ }\Omega, V_{CC} = 400\text{ V},$ $V_p = 650\text{ V}, V_{GE} = 15\text{ V to } 0\text{ V}, T_J = 175\text{ }^\circ\text{C}$					
ANTI-PARALLEL DIODE							
Diode reverse recovery time	t_{rr}	$I_F = 50\text{ A}, di_F/dt = 500\text{ A}/\mu\text{s}$ $V_{rr} = 200\text{ V}, T_J = 25\text{ }^\circ\text{C}$	-	73	-	ns	
Diode peak reverse current	I_{rr}		-	13	-	A	
Diode recovery charge	Q_{rr}		-	465	-	nC	
Diode reverse recovery time	t_{rr}	$I_F = 50\text{ A}, di_F/dt = 500\text{ A}/\mu\text{s}$ $V_{rr} = 200\text{ V}, T_J = 125\text{ }^\circ\text{C}$	-	146	-	ns	
Diode peak reverse current	I_{rr}		-	28	-	A	
Diode recovery charge	Q_{rr}		-	2064	-	nC	



THERMAL AND MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Operating junction temperature range	T_J		-40	-	175	°C
Storage temperature range	T_{Stg}		-40	-	125	
Junction to case per leg	IGBT		-	-	0.35	°C/W
	Diode					
Case to sink per module (conductive grease applied)	R_{thCS}		-	0.05	-	
Mounting torque	Power terminal screw: M5		2.5	-	5.0	
	Mounting screw: M6		3.0	-	5.0	
Weight			-	150	-	g

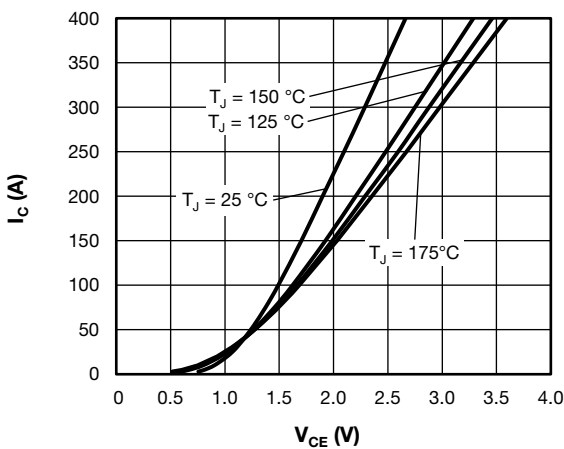


Fig. 1 - Typical IGBT Output Characteristics, $V_{GE} = 15\text{ V}$

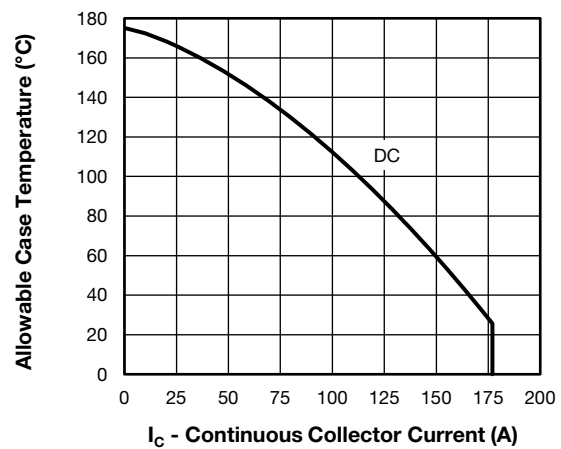


Fig. 3 - Maximum IGBT Continuous Collector Current vs. Case Temperature

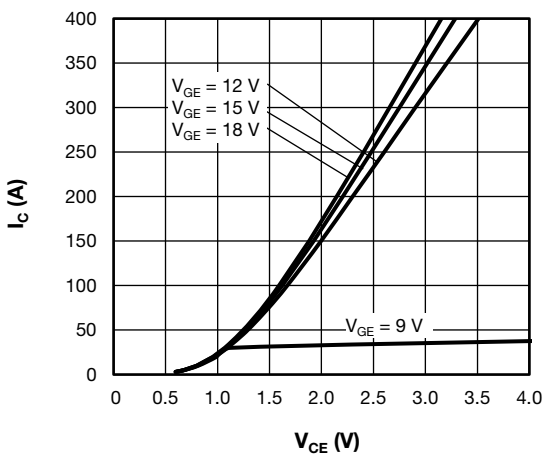


Fig. 2 - Typical IGBT Output Characteristics, $T_J = 125\text{ °C}$

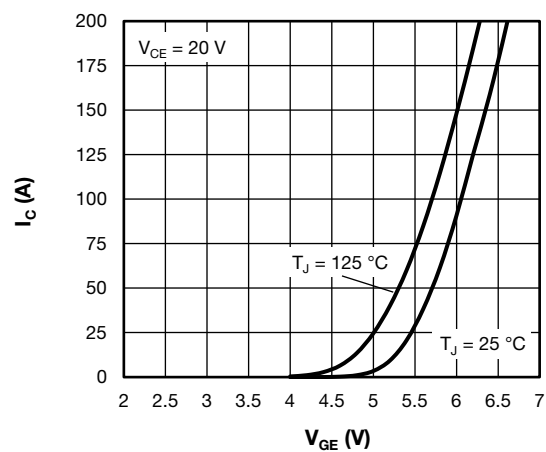


Fig. 4 - Typical IGBT Transfer Characteristics

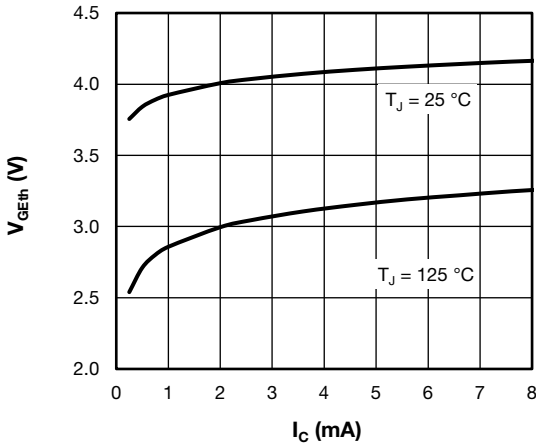


Fig. 5 - Typical IGBT Threshold Voltage

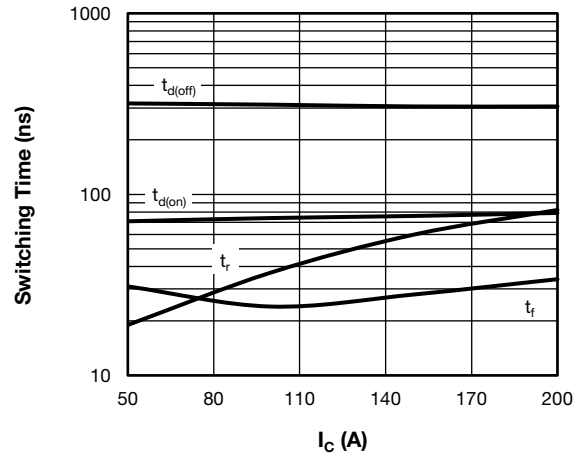


Fig. 8 - Typical Trench IGBT Switching Time vs. I_C (with Antiparallel Diode)
 $T_J = 125\text{ °C}$, $V_{CC} = 300\text{ V}$, $R_g = 4.7\ \Omega$, $V_{GE} = +15\text{ V} / -15\text{ V}$, $L = 500\ \mu\text{H}$

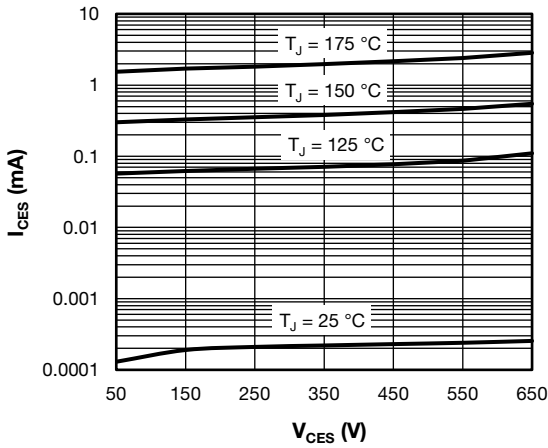


Fig. 6 - Typical IGBT Zero Gate Voltage Collector Current

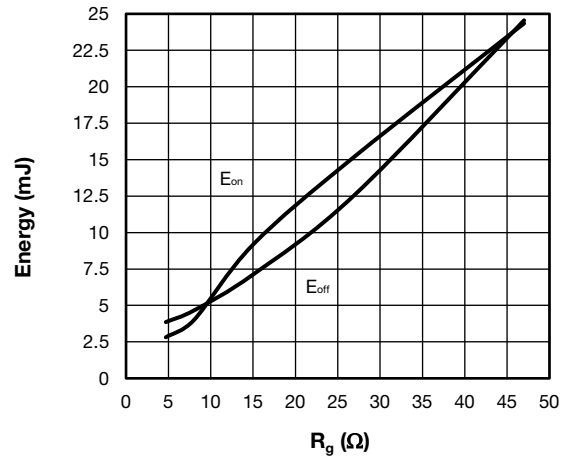


Fig. 9 - Typical Trench IGBT Energy Loss vs. R_g (with Antiparallel Diode)
 $T_J = 125\text{ °C}$, $V_{CC} = 300\text{ V}$, $I_C = 200\text{ A}$, $V_{GE} = +15\text{ V} / -15\text{ V}$, $L = 500\ \mu\text{H}$

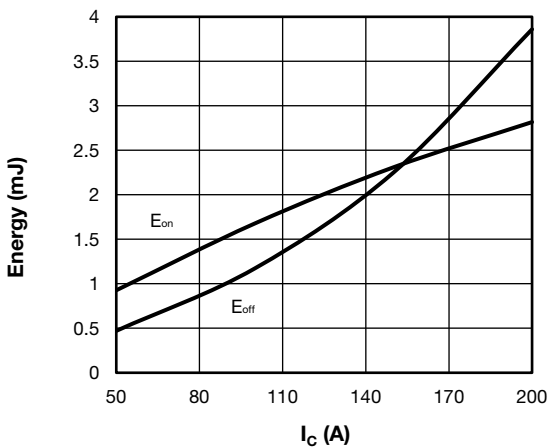


Fig. 7 - Typical Trench IGBT Energy Loss vs. I_C (with Antiparallel Diode)
 $T_J = 125\text{ °C}$, $V_{CC} = 300\text{ V}$, $R_g = 4.7\ \Omega$, $V_{GE} = +15\text{ V} / -15\text{ V}$, $L = 500\ \mu\text{H}$

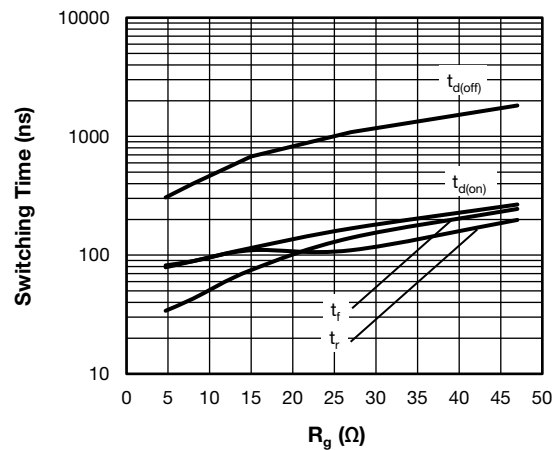


Fig. 10 - Typical Trench IGBT Switching Time vs. R_g (with Antiparallel Diode)
 $T_J = 125\text{ °C}$, $V_{CC} = 300\text{ V}$, $I_C = 200\text{ A}$, $V_{GE} = +15\text{ V} / -15\text{ V}$, $L = 500\ \mu\text{H}$

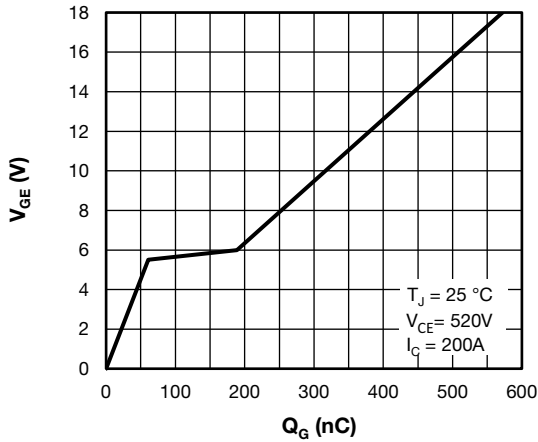


Fig. 11 - Typical Trench IGBT Gate Charge vs. Gate to Emitter Voltage

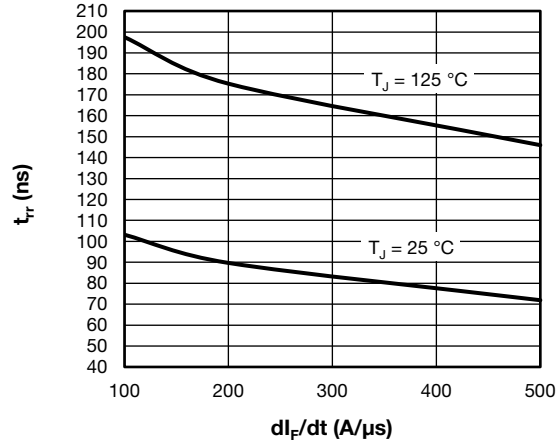


Fig. 14 - Typical Diode Reverse Recovery Time vs. dI_F/dt
 $V_{rr} = 200\text{ V}, I_F = 50\text{ A}$

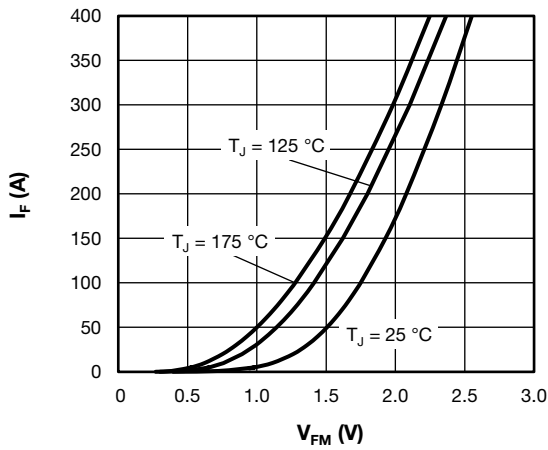


Fig. 12 - Typical IGBT Switching Time vs. I_C

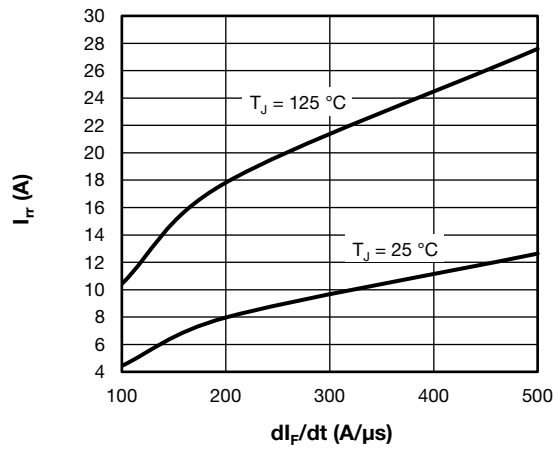


Fig. 15 - Typical Diode Reverse Recovery Current vs. dI_F/dt
 $V_{rr} = 200\text{ V}, I_F = 50\text{ A}$

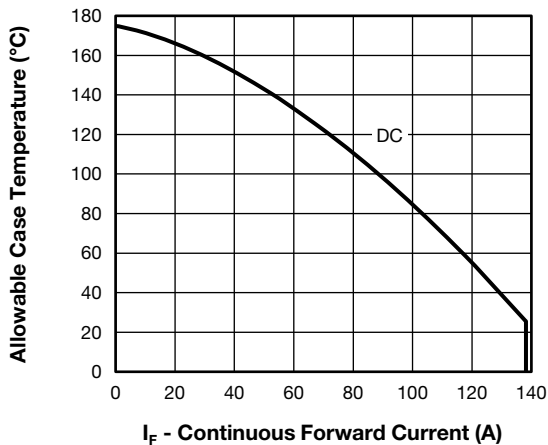


Fig. 13 - Maximum Diode Continuous Forward Current vs. Case Temperature

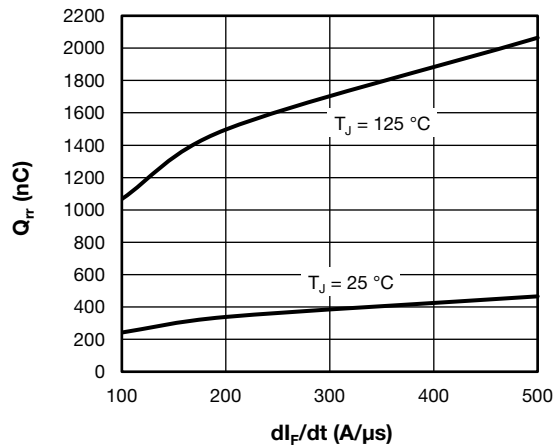


Fig. 16 - Typical Diode Reverse Recovery Current vs. dI_F/dt
 $V_{rr} = 200\text{ V}, I_F = 50\text{ A}$

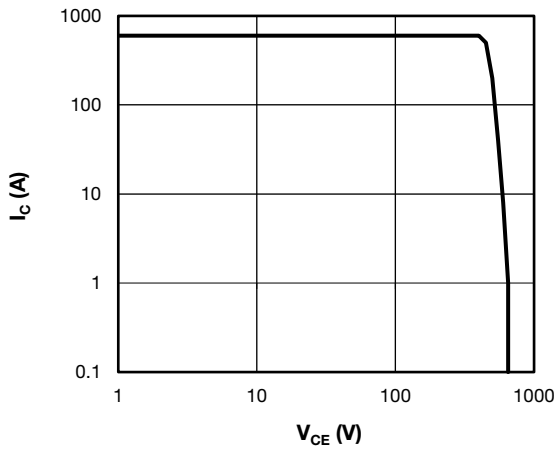


Fig. 17 - Typical Trench IGBT Reverse BIAS SOA
 $T_J = 175\text{ }^\circ\text{C}$, $I_C = 600\text{ A}$, $R_g = 27\ \Omega$, $V_{GE} = +15\text{ V} / 0\text{ V}$, $V_{CC} = 400\text{ V}$,
 $V_p = 650\text{ V}$

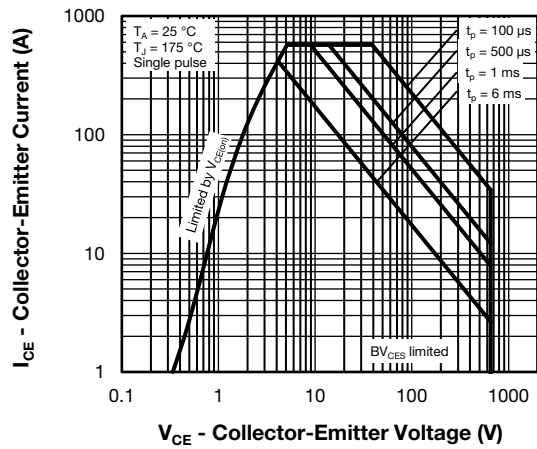


Fig. 18 - Trench IGBT safe Operating Area

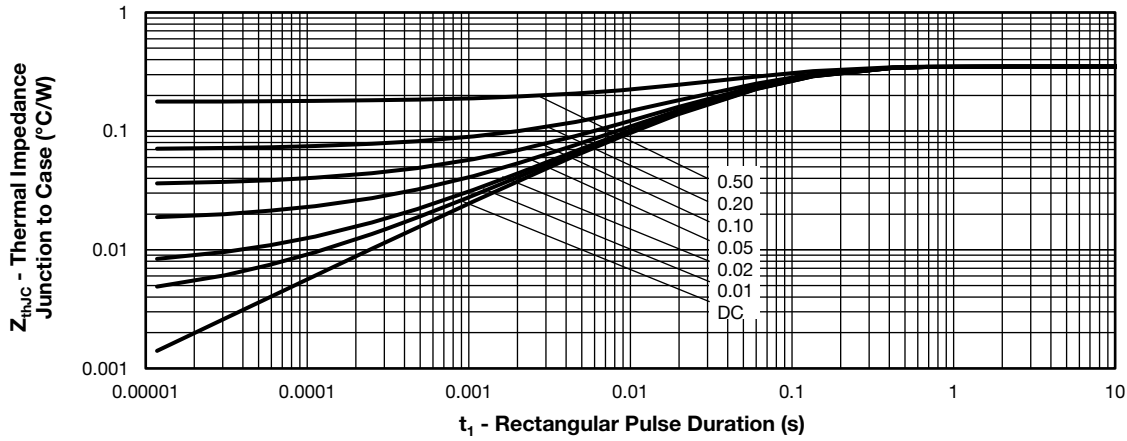


Fig. 19 - Maximum Trench IGBT Thermal Impedance Z_{thJC} Characteristics

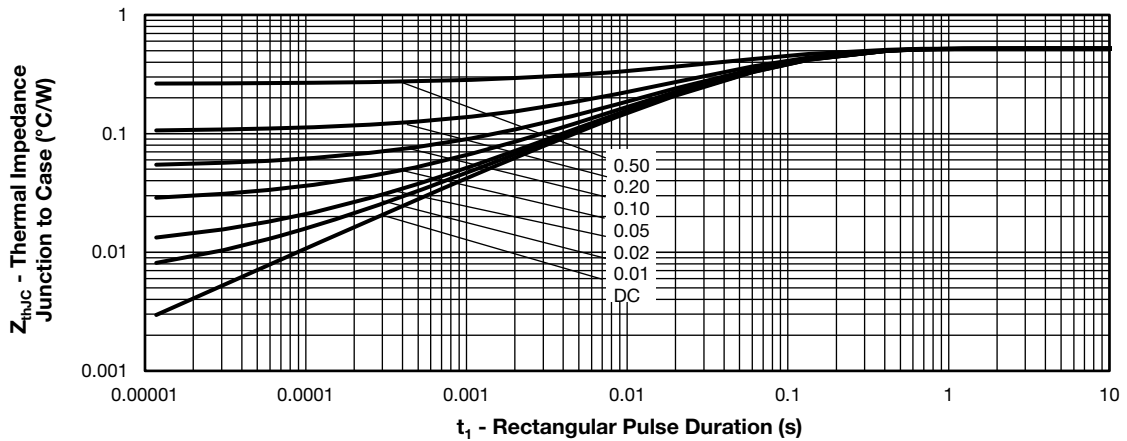
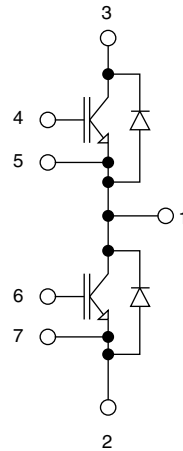


Fig. 20 - Maximum Diode Thermal Impedance Z_{thJC} Characteristics



CIRCUIT CONFIGURATION



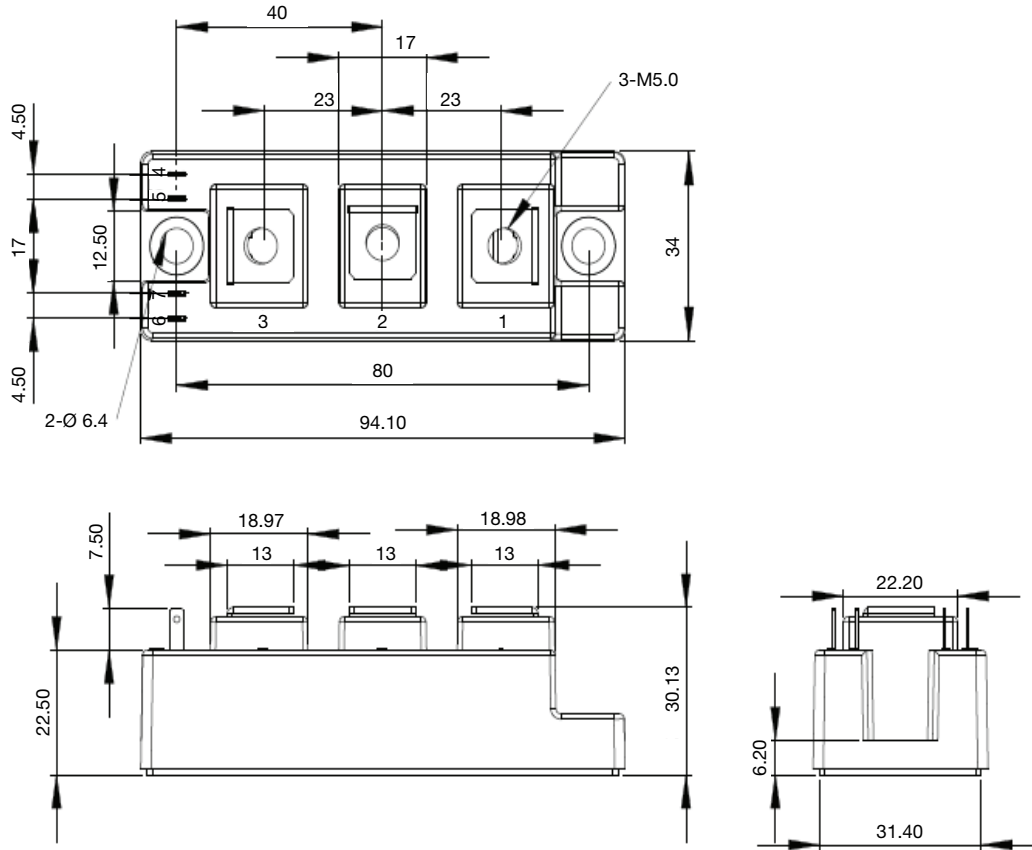
ORDERING INFORMATION TABLE

Device code	VS-	G	T	200	T	P	065	U
	1	2	3	4	5	6	7	8

- 1** - Vishay Semiconductors product
- 2** - Insulated gate bipolar transistor (IGBT)
- 3** - T = trench IGBT
- 4** - Current rating (200 = 200 A)
- 5** - Circuit configuration (T = half bridge)
- 6** - Package indicator (P = INT-A-PAK IGBT)
- 7** - Voltage rating (065 = 650 V)
- 8** - Speed/type (U = ultrafast)



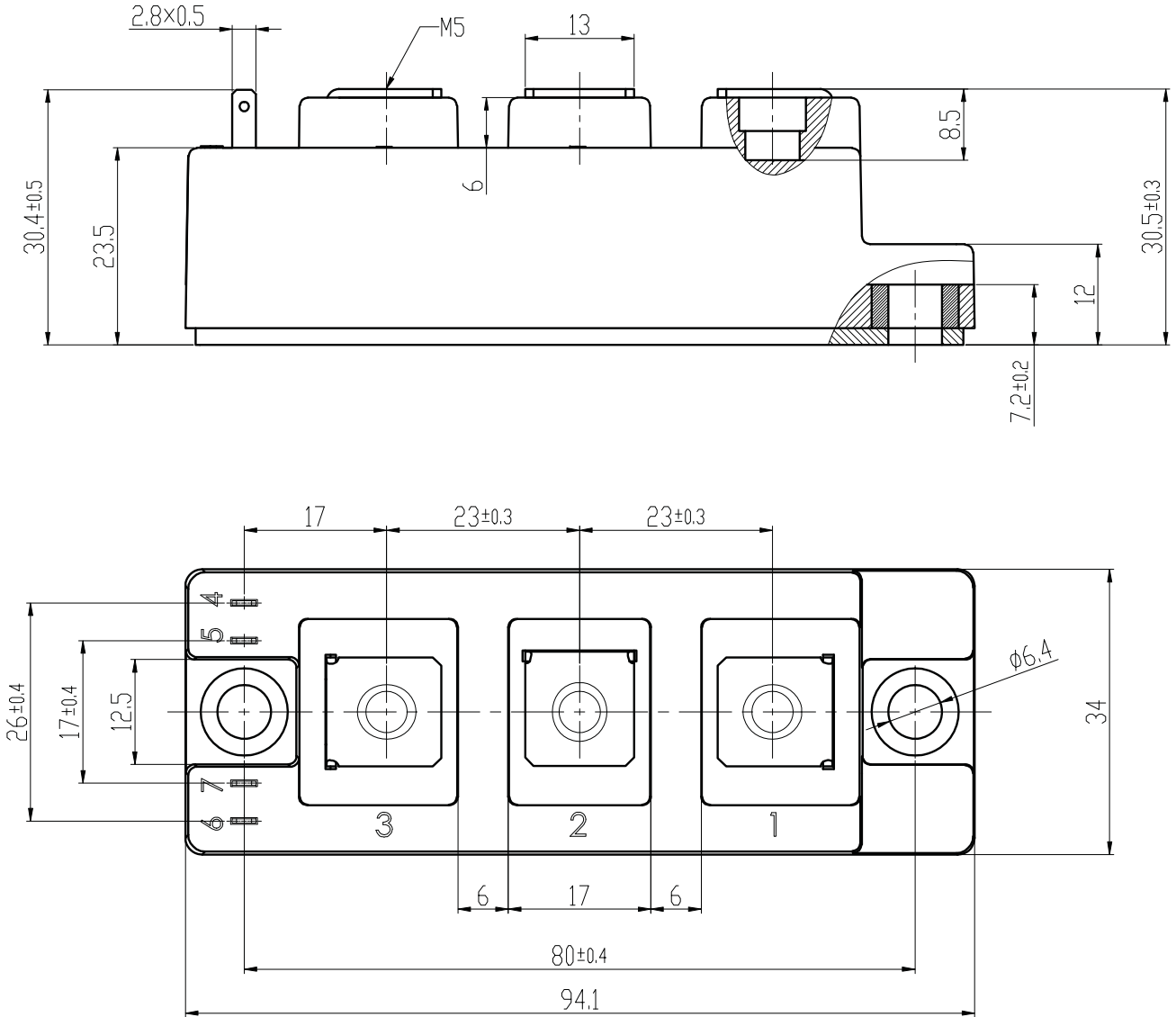
DIMENSIONS in millimeters





INT-A-PAK

DIMENSIONS in millimeters (inches)





Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Hyperlinks included in this datasheet may direct users to third-party websites. These links are provided as a convenience and for informational purposes only. Inclusion of these hyperlinks does not constitute an endorsement or an approval by Vishay of any of the products, services or opinions of the corporation, organization or individual associated with the third-party website. Vishay disclaims any and all liability and bears no responsibility for the accuracy, legality or content of the third-party website or for that of subsequent links.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.